

Wafer Cutting Machine - WCM



Better by design...

Manual Wafer Cutting Machine (WCM)

The wafer cutting machine WCM is manually operated and cuts wafer blocks to small wafer fingers of predetermined dimensions. The cutter frame and feed bar can be exchanged to produce other size of biscuits. The machine is used for cutting of small scale output.

Wafer Creaming Apparatus (WCR)

It is a simple stenciling apparatus. The Sheet holder is designed to hold the sheet in place and allow desired cream application. A knife is used for depositing a layer of cream for sandwiching the wafer biscuits. The apparatus can be attended by an unskilled operator.



Technical Details

Type	WCM
Size of the plate (in mm approx)	270 x 370
Stack height (in mm)	10 to 70
Minimum cutting width (in mm)	16
Cutting Wire (spring steel) (in mm)	0.5
Connected load (in Kw)	1.5
Dimensions (in mm)	
Length	1450
Width	1130
Height	675
Net Weight (apprx)	110
Shipping volume (CBM)	1.0

Note : The above machines are of low scale manual operation.

Limited level of automation for cutting and creaming can be used in this manual process for better quality products.

*Modifications Reserved

We are constantly guided by our principle of offering our customers better and better machines; to give increased efficiency and higher levels of automation. The technical data and illustrations are subject to change without notice

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